TRAVIT
Dry etch and process simulation software

Dry etch is an extremely complex process. Any help provided by simulation facilitates understanding of the process and optimization of the process conditions.

TRAVIT software simulates dry etch and film deposition, to help process engineers in their work. It takes into account circuit layout, microloading, trenching, footing, dispersion, etc.

Complex multistep processes involving changing etch recipes and film deposition - for example, double patterning and MEMS - can be simulated in a single run.

The output of the software is:

- CDs and CD variation,
- vertical profile during and after the etch
- placement error

Double patterning (SPT)